

Class	Subclass
ISSUE CLASSIFICATION	

FILED UNDER 35 U.S.C. 371

PATENT NUMBER

**U.S. UTILITY Patent Application**

**O.I.P.E.**

PATENT DATE

SCANNED SB 5/2 P.A. 1

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/830434	D F	451	41	3723	Shakeri

APPLICANTS

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TITLE

~~Method and device for polishing semiconductor wafer~~

PTO-204  
12/89

[illegible]

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	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) _____ (Date)		<b>NOTICE OF ALLOWANCE MAILED</b>	
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